Memory Devices



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OVERVIEW OF MEMORY

Three Important Characteristics of Semiconductor Memory:

- Density
 - Amount of data that the memory can store
- (Non-) Volatility
 - Data storage capability if power is disconnected
- Read/write capability
 - Capability to update memory

OVERVIEW OF MEMORY (Cont'd.)

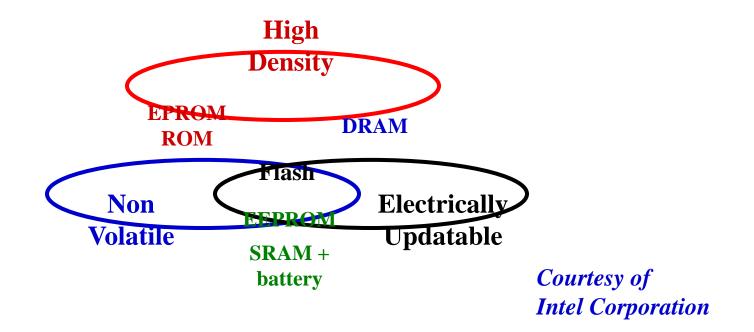
Categories of Semiconductor Storage Cells:

- **SRAM** (static random-access memory)
- DRAM (dynamic random-access memory)
- ROM (read-only memory)
- **EPROM** (electrically programmable ROM)
- **EEPROM** (electrically erasable **PROM**)
- Flash Memory

See next slide for characteristics of each category of memory.

OVERVIEW OF MEMORY (Cont'd.)

Important Semiconductor Memory Characteristics:



RANDOM-ACCESS MEMORY (RAM)

Characteristics of RAM:

- Data can be "written" to RAM
- Stored data can be "read" at any time
- Volatile cannot be used for permanent memory
- Access to any memory location (address) at any moment

Types of RAM:

- SRAM (static RAM) stores data in flip-flop-like cells. Holds 0 or 1 as long as IC has power (volatile).
- DRAM (dynamic RAM) memory cells need refreshing many times per second. Also volatile.

READ-ONLY MEMORY (ROM)

Characteristics of ROM:

- Non-volatile memory is not lost when power is turned off
- Data is stored permanently
- Data stored in ROM can be "read" at any time
- ROM cannot be reprogrammed
- High density

PROGRAMMABLE READ-ONLY MEMORY (PROM)

Data can be programmed or "burned" into a PROM

Types of PROM:

- Mask-programmable ROM (usually simply called ROM)
- Field-programmable ROM (PROM)
- Erasable programmable ROM (EPROM)
- Electrically erasable PROM (EEPROM or E²PROM)
- Flash EEPROM

NONVOLATILE READ/WRITE MEMORY

- SRAM with battery backup
 - Typically a long-life lithium battery
- **NVSRAM** (non-volatile static RAM)
 - Better access speed and overall life than SRAM with battery backup
 - Flash Memory
 - Nonvolatile
 - In-system rewritable (read/write)
 - Highly reliable
 - Low power consumption
 - High density

MEMORY PACKAGING

Common Methods of Packaging Semiconductor Memory:

- **DIP** (dual in-line package)
- **SIP** (single in-line package)
- **ZIP** (zig-zag in-line package)
- **SIMM** (single in-line memory module)
- Memory cards

COMPUTER BULK STORAGE DEVICES

Primary storage - computer's internal storage Secondary storage - external storage

Types of secondary storage devices:

- Mechanical Devices
 - Punched paper card
 - Punched or perforated paper tape
- Magnetic Devices
 - Magnetic tape (sequential-access device)
 - Magnetic drum
 - Hard disk
 - Floppy disk

COMPUTER STORAGE DEVICES

Types of Secondary Storage Devices (cont'd.):

- Optical Devices
 - CD-ROM (Read-only)
 - WORM (write-once, read-many)
 - Read/write
- Semiconductor Devices
 - Flash EEPROM semiconductor

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Thank You...